Form PTO-1595

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To the Honorable Commissioner of Patents and Trademarks: Please record the attached original documents or copy thereof

	1. Name of conveying party(ies):	Name and address of receiving party(ies):
	Cem Basceri 3-1-99	Name: Micron Technology, Inc.
	Husam N. Al-Shareef	Internal Address:
	Additional name(s) of conveying Yes	8000 S. Federal Way Boise, Idaho 83706-9632
	party(ies) attached?	Street Address:
	3. Nature of Conveyance:	8000 S. Federal Way Boise, Idaho 83706-9632
	X Assignment Merger	City: Boise
	Security Agreement Change of Name	Country: U.S.A. Zip: 83706-9632
	Other	, <u>serve seez</u>
	December 3, 1998 and	
	Execution Date: February 23, 1999	Additional names(s) & Yes
		address(es) attached? X No
	4. Application number(s) or patent number(s): ()9 /	259,259
	If this document is being filed together with a new application,	
	application is	<u>February 23, 1999</u>
	A. Patent Application No.(s):	B. Patent No.(s):
		Additional numbers attached? Yes X No
	Name and address of party whom correspondence concerning document should be mailed:	6. Total number of applications and patents involved:
	Name: DICKSTEIN SHAPIRO MORIN & OSHIINSKY LLP	7. Total fee (37 CFR 3.41) \$ 40.00
	Internal Address: Atty. Dkt.: M4065.136/P136	× Enclosed
	Attn: Thomas J. D'Amico	Authorized to be charged to deposit account
	Street Address: 2101 L Street NW	
	City: Washington State: DC Zip: 20037-1526	8. Deposit account number: 04-1073
03	12/1999 DNGUYEN 00000061 09259259	
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	Statement and signature.	
İ	To the best of my knowledge and belief, the foregoin	g information is true and correct and any attached copy
	is a true copy of the original document.	M 1 4 4000
	Thomas J. D'Amico Signature	March 1, 1999 Date
	Reg. No. 28,371	
ļ	Total number of pages including cover sheet, attachn	nents, and document:4
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PATENT REEL: 9803 FRAME: 0883

948450 v1; KBT%01!.DOC

Docket No.: M4065.136 Micron No.: 98-0181.00/US

ASSIGNMENT AND AGREEMENT

For value received, we, Cem Basceri of Boise, Idaho, and Husam N. Al-Shareef of Boise, ID, do hereby sell, assign and transfer to Micron Technology Inc., a corporation of the State of Delaware, having an office at 8000 S. Federal Way, Boise, Idaho 83706-9632, U.S.A., and its successors, assigns and legal representatives, the entire right, title and interest, for the United States of America, in and to certain inventions related to an invention entitled METHOD FOR IMPROVING THE RESISTANCE DEGRADATION OF THIN FILM CAPACITORS described in an application for Letters Patent of the United States, executed by us of even date herewith, and all the rights and privileges in said application and under any and all Letters Patent that may be granted in the United State for said inventions; and we also concurrently hereby sell, assign and transfer to Micron Technology, Inc. the entire right, title and interest in and to said inventions for all countries foreign to the United States, including all rights of priority arising from the application aforesaid, and all the rights and privileges under any and all forms of protection, including Letters Patent, that may be granted in said countries foreign to the United States for said inventions.

We authorize Micron Technology, Inc. to make application for such protection in its own name and maintain such protection in any and all countries foreign to the United States, and to invoke and claim for any application for patent or other form of protection for said inventions, without further authorization from us, any and all benefits, including the right of priority provided by any and all treaties, conventions, or agreements.

We hereby consent that a copy of this assignment shall be deemed a full legal and formal equivalent of any document which may be required in any country in proof of the right of Micron Technology, Inc. to apply for patent or other form of protection for said inventions and to claim the aforesaid benefit of the right of priority.

We request that any and all patents for said inventions be issued to Micron Technology, Inc. in the United States and in all countries foreign to the United States, or to such nominees as Micron Technology, Inc. may designate.

JWGF01!.SAM-928527 (M4065.136)

PATENT REEL: 9803 FRAME: 0884

Docket No.: M4065.136 Micron No.: 98-0181.00/US

We agree that, when requested, We shall, without charge to Micron Technology, Inc. but at its expense, sign all papers, and do all acts which may be necessary, desirable or convenient in connection with said applications, patents, or other forms of protection. United States of America State of _________)ss.:
County of _________) On this 3 day of Ocember, 1998, before me personally came Cem Basceri, to me known to be the individual described in and who executed the foregoing instrument, and acknowledged execution of the same. Husam N. Al-Shareef Date: _____ United States of America State of ________)ss.:
County of ________) On this ____ day of _____, 1998, before me personally came Husam N. Al-Shareef, to me known to be the individual described in and who executed the foregoing instrument, and acknowledged execution of the same. Notary Public

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Micron No.: 98-0181.00/US

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

Please address all correspondence to Thomas J. D'Amico of Dickstein Shapiro Morin & Oshinsky LLP located at 2101 L Street, NW, Washington, DC 20037-1526. Telephone calls should be made to Thomas J. D'Amico by dialing (202) 828-2232.

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Inventor's signature Date		
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Full name of 2nd joint inventor: Husam N. Al-Shareef		
Inventor's signature Husam Als Garaf Date 2/23/1999		
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Citizenship: United States of America		
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JWGZ011.5AM-928547 (M4065.136)

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REEL: 9803 FRAME: 0886